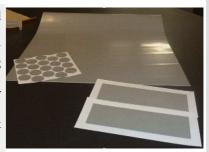


TIM / New Phase Change Material / Xp45 Series

High Performance

The Xp45-W-series is cost-efficient, electrically non-insulating TIM change material enriched with a high-heat conductive filler, solvent-and silicone-free, high-performance. Through the development of this new and unique formulation, the interface is already providing a very efficient thermal transmission by phase change at normal operating temperatures, where a uniform connection line is maintained during the expansion process. With the result that air is efficiently expelled to the outside and any surface irregularities or flatness conditions-which are present across the interface-can be minimized.

Only through efficient and reliable contact connection between heat generation and heat sink can an optimal thermal be carried out in the heatsink or the housing tray.



PROPERTIES

Perfect thermal and mechanical contact, Silicone-free, Stable, no migrating, desiccation, evaporation. Only low tightening torque required. Easy cleaning by Isopropyl alcohol. Coating thickness warranted process unity and long term reliability. Solution for many types of surfaces. A better alternative of a thermal paste, a replacement of thermal grease / TIM on baseplate of insulated cases or packages

AVAILABILITY

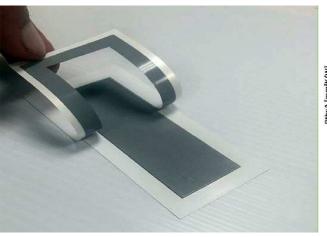
Standard Sheets 300x600 mm alter 400 x 600 /1000 mm Roll - dimension according to customer request specification Die cut parts, Formats on request. Material is not tacky Thickness 0,10 /0,20 /0,30 mm

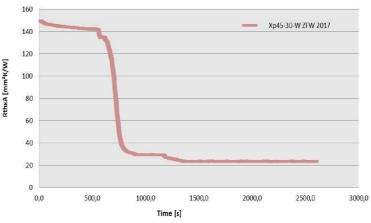
APPLICATION EXAMPLES

Heat transfer of microprocessors, LEDs, MOSFET, IGBT, Diode, Thyristor, Hybrid modules in electrical insulated discreate packages, modules. Modules without Cu base plates - Ceramic bases, thermally demanding, high frequency, traction drives inverters, power supplies, servo drive, battery units, UPS, etc.

Property	Unit	Xp45-W-10	Xp45-W-20	Xp45-W-30
Material		Phase change, Silicone free	Phase change, Silicone free	Phase change, Silicone free
Colour		Grey	Grey	Grey
Thickness:	mm	0,100	0,200	0,300
Thermal				
Thermal Conductivity	W / m*K	3,50	3,50	3,50
Thermal Resistance @ 100 PSI	°C-inch²/W	0,0064	0,0069	0,0076
T. Resistance / @ 40PSI / @ 10 PSI	°C-inch²/W	0,0087 / 0,0138	0,0093 / 0,0148	0,010 / 0,0158
Phase Change Temperature	°C	cca 45 / softens from 35°C	cca 45 / softens from 35°C	cca 45 / softens from 35°C
Operating Temperature	°C	from -40 °C to 140 °C	from -40 °C to 140 °C	from -40 °C to 140 °C
Max Storage Temperature	°C	35	35	35

Test Methods: 1ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.







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